



DCPMC64

Dual CompactPCI® 64-bit PMC Carrier Module

Features

- Dual PMC sites
- 32/64-bit 33/66MHz PCI bus
- PCI 6154 Transparent PCI/PCI Bridge
- Conduction-cooled or ruggedized
- Dedicated I/O bus between each PMC site and the backplane

Specifications

Temperature

- Operating: -40°C to 85°C ambient
- Storage: -55°C to 105°C

Humidity

- 5% to 95% (non-condensing)

Cooling

- Conduction-cooled (-N version) through heat frame
- Convection-cooled (-R version) through system cooling fans

Power Requirements

- +3.3V (+5V and ±12V determined by installed PMC modules)
- PMC VIO can be configured as +3.3V or +5V

Form Factor

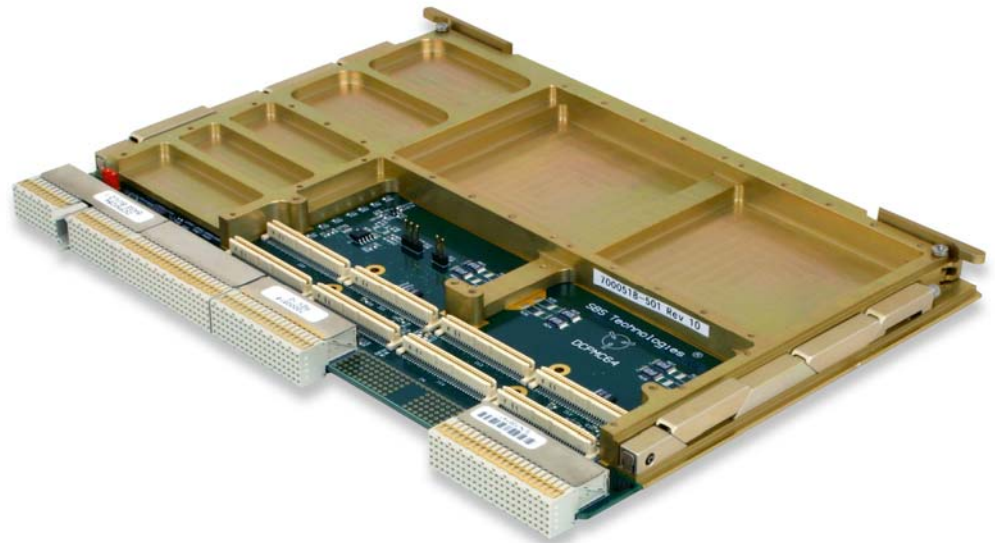
- 6U

Dimensions

- Height: 233 mm (9.2 in.)
- Length: 160 mm (6.2 in.)

Warranty

- 2 year warranty



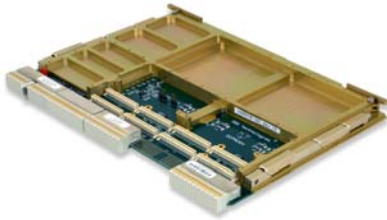
DCPMC64 is a rugged Dual CompactPCI 64-bit PMC (DCPMC64) carrier module in 6U form factor that can accommodate two PMC modules for increasing I/O capability to a system.

The DCPMC64 can connect two IEEE 1386.1 PMC modules to any standard CompactPCI backplane through a 32/64-bit, 33/66MHz cPCI bus. The DCPMC64 uses PLX Technology's® PCI 6154 transparent PCI/PCI Bridge for data transactions from the PCI bus (system host) to two standard PMC sites.

Each PMC site can send I/O data directly to the CompactPCI backplane through its I/O connector and PMC I/O bus.

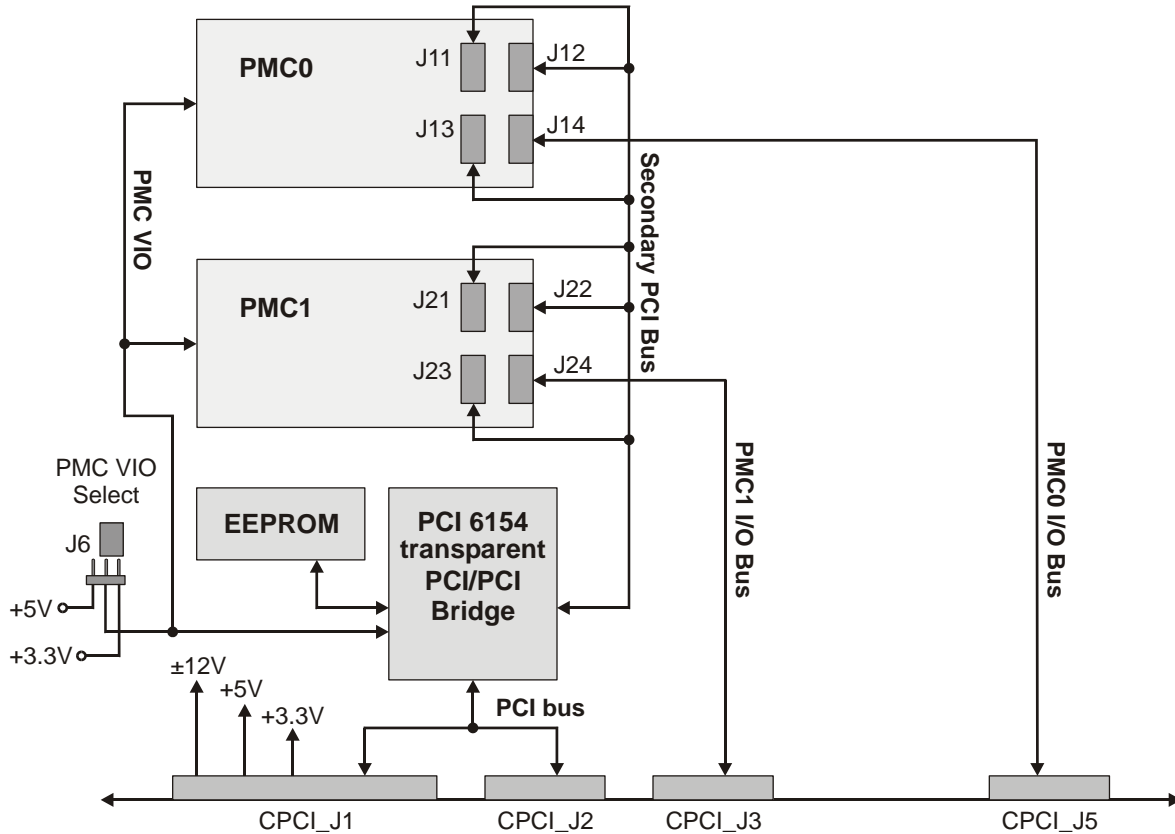
The conduction-cooled DCPMC64 uses a custom heat frame to conduct heat from the board and PMC modules to a conduction-cooled system chassis.

The DCPMC64 is backwards compatible with the DCPMC.



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Block Diagram



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